

Darlington Power Transistor

DPAK For Surface Mount Applications

MJD44E3, NJVMJD44E3T4G

Designed for general purpose power and switching output or driver stages in applications such as switching regulators, converters, and power amplifiers.

Features

- Electrically Similar to Popular D44E3 Device
- High DC Gain – 1000 Min @ 5.0 Adc
- Low Sat. Voltage – 1.5 V @ 5.0 Adc
- Compatible With Existing Automatic Pick and Place Equipment
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings:
 - ◆ Human Body Model, 3B > 8000 V
 - ◆ Machine Model, C > 400 V
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Packages*

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	80	Vdc
Emitter-Base Voltage	V_{EB}	7	Vdc
Collector Current – Continuous	I_C	10	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

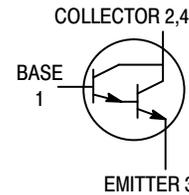
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

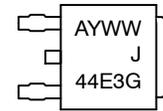
NPN DARLINGTON SILICON POWER TRANSISTORS 10 AMPERES 80 VOLTS, 20 WATTS



DPAK
CASE 369C
STYLE 1



MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
J44E3 = Device Code
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MJD44E3T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD44E3T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MJD44E3, NJVMJD44E3T4G

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.25	$^{\circ}C/W$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	71.4	$^{\circ}C/W$
Lead Temperature for Soldering	T_L	260	$^{\circ}C$

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector Cutoff Current ($V_{CE} = \text{Rated } V_{CEO}, V_{BE} = 0$)	I_{CES}	-	-	10	μA
Emitter Cutoff Current ($V_{EB} = 7 \text{ Vdc}$)	I_{EBO}	-	-	1	μA

ON CHARACTERISTICS

Collector-Emitter Saturation Voltage ($I_C = 5 \text{ Adc}, I_B = 10 \text{ mAdc}$) ($I_C = 10 \text{ Adc}, I_B = 20 \text{ mAdc}$)	$V_{CE(sat)}$	-	-	1.5 2	Vdc
Base-Emitter Saturation Voltage ($I_C = 5 \text{ Adc}, I_B = 10 \text{ mAdc}$)	$V_{BE(sat)}$	-	-	2.5	Vdc
DC Current Gain ($V_{CE} = 5 \text{ Vdc}, I_C = 5 \text{ Adc}$)	h_{FE}	1000	-	-	-

DYNAMIC CHARACTERISTICS

Collector Capacitance ($V_{CB} = 10 \text{ Vdc}, f_{test} = 1 \text{ MHz}$)	C_{cb}	-	-	130	pF
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SWITCHING TIMES

Delay and Rise Times ($I_C = 10 \text{ Adc}, I_{B1} = 20 \text{ mAdc}$)	$t_d + t_r$	-	0.6	-	μs
Storage Time ($I_C = 10 \text{ Adc}, I_{B1} = I_{B2} = 20 \text{ mAdc}$)	t_s	-	2	-	μs
Fall Time ($I_C = 10 \text{ Adc}, I_{B1} = I_{B2} = 20 \text{ mAdc}$)	t_f	-	0.5	-	μs

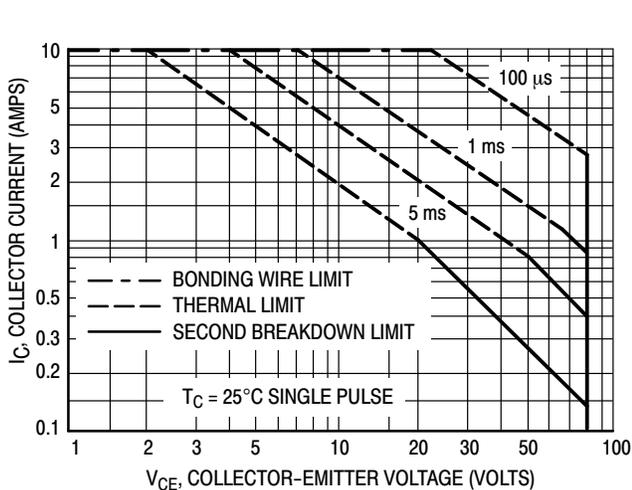


Figure 1. Maximum Forward Bias Safe Operating Area

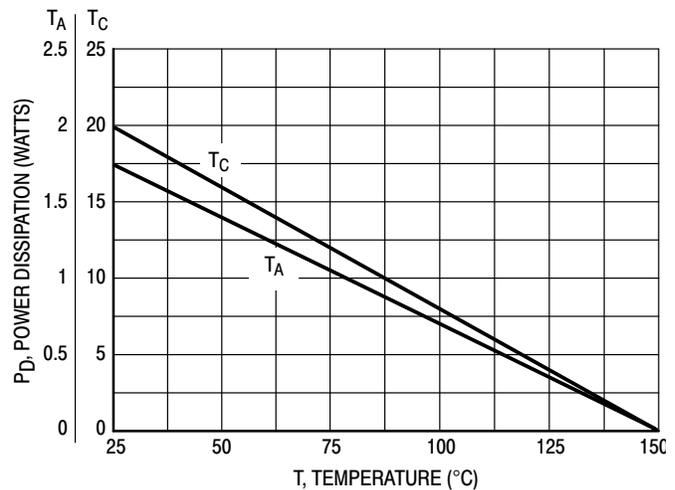
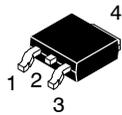


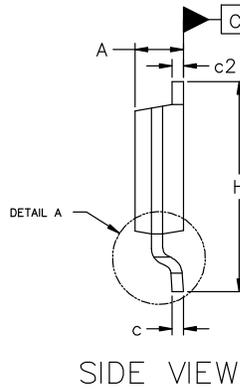
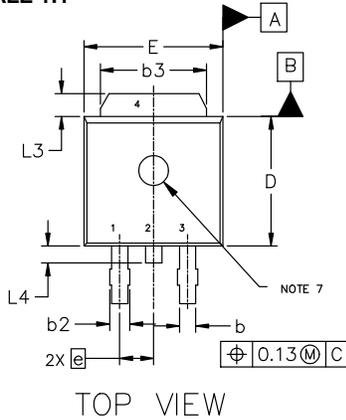
Figure 2. Power Derating



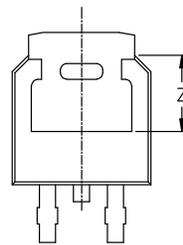
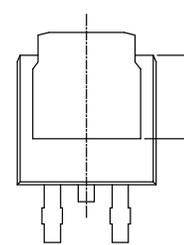
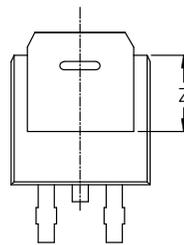
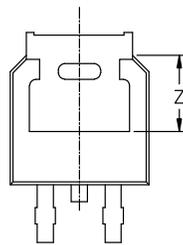
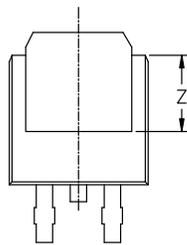
DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE J

DATE 12 AUG 2025

SCALE 1:1



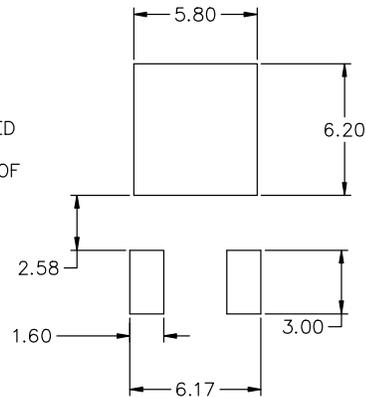
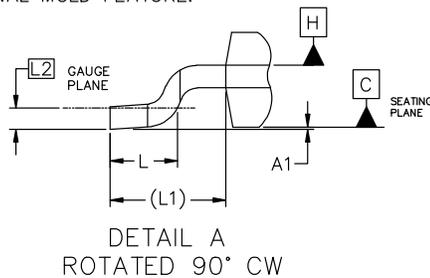
MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



ALTERNATE CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

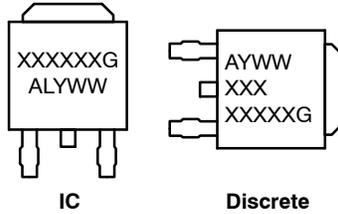
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DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE J

DATE 12 AUG 2025

**GENERIC
MARKING DIAGRAM***



- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

- | | | | | |
|--|--|---|---|--|
| <p>STYLE 1:
 PIN 1. BASE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR</p> | <p>STYLE 2:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE
 4. DRAIN</p> | <p>STYLE 3:
 PIN 1. ANODE
 2. CATHODE
 3. ANODE
 4. CATHODE</p> | <p>STYLE 4:
 PIN 1. CATHODE
 2. ANODE
 3. GATE
 4. ANODE</p> | <p>STYLE 5:
 PIN 1. GATE
 2. ANODE
 3. CATHODE
 4. ANODE</p> |
| <p>STYLE 6:
 PIN 1. MT1
 2. MT2
 3. GATE
 4. MT2</p> | <p>STYLE 7:
 PIN 1. GATE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR</p> | <p>STYLE 8:
 PIN 1. N/C
 2. CATHODE
 3. ANODE
 4. CATHODE</p> | <p>STYLE 9:
 PIN 1. ANODE
 2. CATHODE
 3. RESISTOR ADJUST
 4. CATHODE</p> | <p>STYLE 10:
 PIN 1. CATHODE
 2. ANODE
 3. CATHODE
 4. ANODE</p> |

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